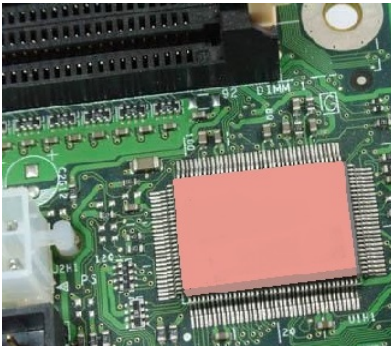


Gap Pad - Thermal Conductive Pad

SD-GP3.2 (K=3.2, without glass fabric)

Features and Benefits

- Thermal conductivity: 3.2 W/m·K
- Soft and highly compliant
- Low thermal resistance at low pressure
- Naturally tacky for easy assembly



SD-GP3.2 is a 3.2 W/m·K soft gap filler thermal interface material with great thermal performance and high compliancy. SD-GP3.2 is well suited for high performance in low-stress applications. And it maintains a conformable yet elastic nature that allows for excellent interfacing and wet-out characteristics, even to surfaces with high roughness or topography.

TYPICAL PROPERTIES		
PHYSICAL	TYPICAL RESULTS	TEST METHOD
Color	Light Red	Visual
Reinforcement Carrier	None	-
Thickness Range	0.5 to 6 mm	ASTM D374
Density	3.0 g/cc	ASTM D792
Tensile strength	0.08Mpa	ASTM D412
Hardness (Shore 00)	40	ASTM D2240
ELECTRICAL		
Dielectric Breakdown Voltage @1mm	> 6KV	ASTM D149
Dielectric Constant (1MHz)	5.5	ASTM D150
Volume Resistivity (Ω -m)	10^{11}	ASTM D257
Flame Rating	V-0	UL 94
THERMAL		
Thermal Conductivity (W/m·K)	3.2	ASTM D5470
Thermal Impedance @1mm, 20psi	0.35 °C·in. ² /W	ASTM D5470
Continuous Use Temp.	-50°C to 180°C	-

Typical Applications Include:

- Semiconductors to heat sink
- Telecommunications equipment
- Consumer electronics
- LCD and PDP flat panel TV

Available Forms:

- Sheet form , max width 300mm
- die-cut parts available, can be customized
- Fiberglass reinforce when thickness less than 1.0mm